In the Specification:

Page 5, second full paragraph:

The second object of the invention, discussed above, may be achieved by providing a smart card comprising a semiconductor device in accordance with the teachings of the invention. Such a smart card will then be protected against visual inspection from an unwanted outside source. Preferably such a smart card comprises a semiconductor device that includes a light-sensitive element so as to protect the memory of the smart card against visual inspection after opening of the semiconductor device.

Paragraph bridging pages 6 and 7:

In Figure 2, a security coating 14 in accordance with the invention is provided on the passivation layer 13. The matrix of the coating 14 comprises molecules of a first material, in this case monoaluminum phosphate $Al(OPO_3H_2)_3$, which molecules are bonded to the surface of the passivation layer and to each other. The bonds are formed by condensation of hydroxyl groups. In order to clarify the molecular process of bonding, Figure 2 shows the molecules of the matrix and the particles which act as the first or the second filler in a transition state to bonding. In this state the coating has an internal structure as in the bonded state, but no condensation has taken place yet. The encircled pairs of hydroxyl groups must be understood to change on bonding into an oxygen bond and in a liberated H_2O molecule. The matrix also comprises particles of TiO_2 and TiN which act as the first and the second filler in the matrix. The particles preferably have an average particle size of between 50 nm and 1 μm. The TiN-particles have a oxidized surface, e.g. their surface mainly comprises TiO_2, and they can be bonded to the matrix as easily as the TiO_2-particles.